# High-Frequency Interposer Socket

## FEATURES

- Pressure-mount plunge to board interposer.
- Multiple configurations: MLF, QFN, CSP, BGA, MSOP, QSOP, QFP, and more.
- Very low inductance per contact site.
- High cycle life with easy maintenance.
- Manual or Automated Handler applications.
- High-Frequency Application: -1.0dB to 40GHz (0.5mm pitch).

## GENERAL SPECIFICATIONS

- SOCKET BODY MATERIAL: specified at time of quotation
- INTERPOSER: etched Kapton with Au-plated Pads and Compliant Pads on bottom side
- AVAILABLE PITCHES: down to 0.32mm
- CONTACT SELF-INDUCTANCE: 0.11nH (0.50mm pitch CSP)
- VSWR <2:1 to 40GHz
- CONTACT RESISTANCE: <20 mΩ
- CONTACT FORCE: 15-25 grams
- CURRENT CAPACITY: 2 amps (continuous) 4 amps (peak)
- CONTACT LIFE: 50,000-100,000
- SIGNAL PATH LENGTH: 0.011 (with compliant pads)
- MUTUAL CAPACITANCE: 0.015pF

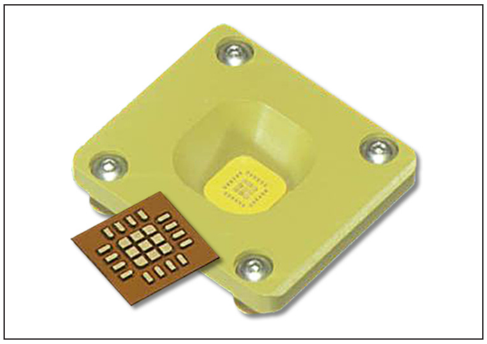
## GENERAL SPECIFICATIONS

- SUGGESTED PCB PADS: Au-plated
- MOUNTING FORCE: 5-oz inches [0.035Nm]

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

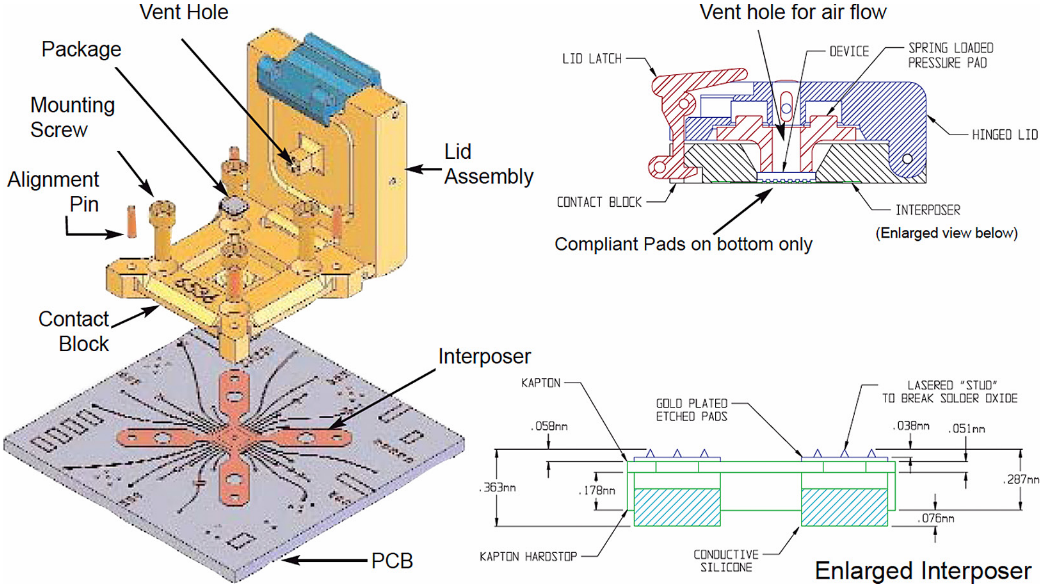
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



**CUSTOMIZATION**: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE**: Aries reserves the right to change product general specifications without notice.

## ORDERING INFORMATION

Consult Facotry for P/N



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